Explanation of Document and ADDENDUM Structure

Dear MIFARE Customer, May 2000

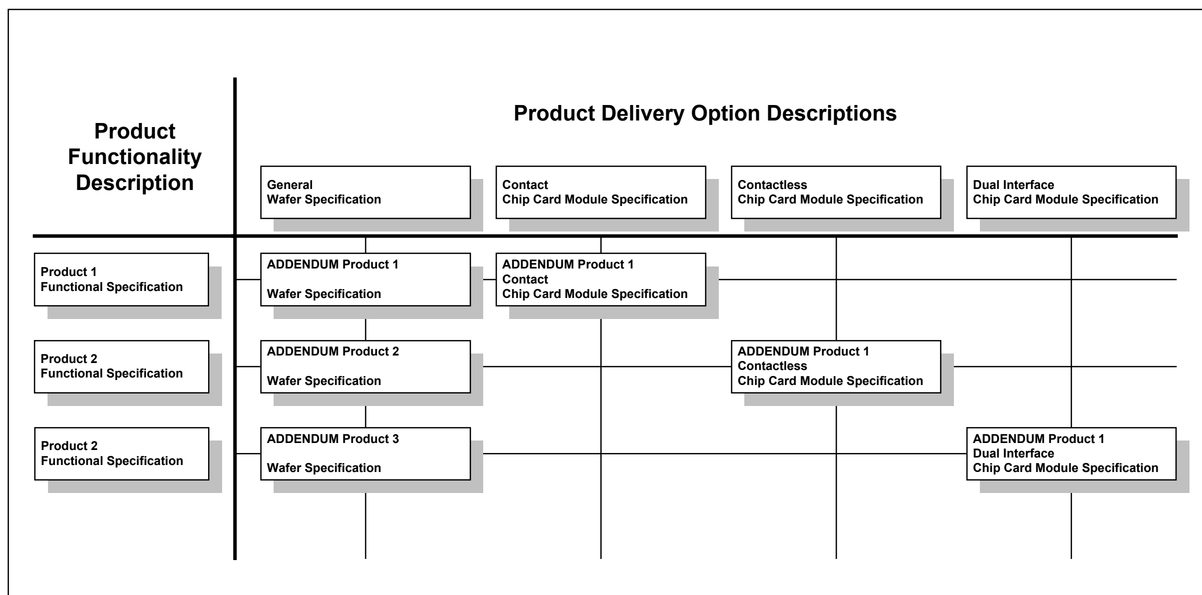
Philips Semiconductors offers a variety of contactless smart card IC's for the MIFARE architecture platform.
In parallel Philips Semiconductor constantly develops new packages for these ICs meeting the specific demands of chip card production.
Therefore MIFARE contactless smart card ICs are available in different delivery options. E.g.

- on wafer; sawn or sawn & bumped; 6“ or 8“
- in packages suitable for card manufacturing, generally called modules.

The documentation for these products is structured as follows:

- The functionality of a MIFARE contactless smart card IC is covered by the *Functional Specification* . This contains information independent of the delivery option.
- For each of the delivery options a general document dealing in detail with its relevant characteristics is available. E.g.: General Wafer Specification, Contactless Chip Card Module Specification,... This contains information independent of the IC.
- Information covering IC specifics in the appropriate delivery option is described in the so-called ADDENDUM. E.g. Ordering number, electrical characteristics in the specific package etc.

The picture below gives an general overview of this documentation structure.



Note: Documents formerly titled ‘Physical Specification’ have been renamed to ‘ADDENDUM - Wafer Specification’.